

What is claimed is:

1. The use of thermoplastic hot-melt adhesives to produce component layers of smart cards.
2. The use of thermoplastic hot-melt adhesives to produce transponders.
3. The use as claimed in claim 1 or 2, wherein the hot-melt adhesive has a composition based on polyamide, polyurethane, polyester, atactic polypropylene (APP), ethylene-vinyl acetate (EVA) copolymers, low molecular mass polyethylene copolymers, or blends thereof.
4. A process for producing card bodies comprising electronic circuits (smart cards), which comprises using as component layer material a thermoplastic hot-melt adhesive whose processing viscosity is situated between 100 and 100 000 mPa.s (Brookfield, RVDV II + Thermosel).
5. The process as claimed in claim 4, wherein the component layer is molded in the low-pressure injection molding process at pressures between 1 and 50 bar and processing temperatures between 80°C and 250°C, preferably between 100°C and 230°C.
6. A multilayer card body, wherein the layer carrying electronic circuits is composed of a thermoplastic hot-melt adhesive.

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